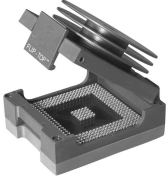
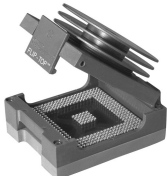


Table of Models

	<p>Description: Molded Socket (FRG, 1.27mm pitch) Material: High Temp. Liquid Crystal Polymer (LCP) Index: -40°C to 260°C (-40°F to 500°F)</p>	<p>Socket Size: 3mm wider and 10mm longer than BGA device.</p>
	<p>Description: Molded Socket (FRH, 1.00mm pitch) Material: High Temp. Liquid Crystal Polymer (LCP) Index: -40°C to 260°C (-40°F to 500°F)</p>	<p>Socket Size: 3mm wider and 10mm longer than BGA device (for device packages larger than 15mm square).*</p>

Features:

- Designed to save space on new and existing PC boards in test, development, programming and production applications.
- No external hold-downs or soldering of BGA device required.
- AIC exclusive solder ball terminals offer superior processing.
- Uses same footprint as BGA device.
- Available with integral, finned heat sink or coin screw clamp assembly.

Specifications:

Terminals:

Brass - Copper Alloy
(C36000) ASTM-B-16

Contacts:

Beryllium Copper
(C17200) ASTM-B-194

Plating:

G - Gold over Nickel

Terminal Support:

Polyimide Film

Spring Material:

Stainless Steel

Heat Sink/Coin Screw and Support Plate Material:

Aluminum

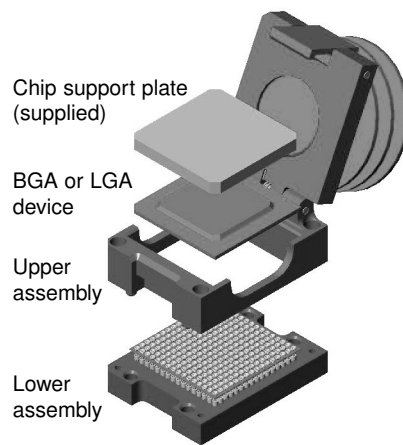
Solder Ball:

Standard: 63Sn/37Pb
 Lead-free: 95.5Sn/4.0Ag/0.5Cu

FRG replaces FTG.

* For device packages smaller than 15mm square, the socket size is $X = .709/(18.00)$ and $Y = .984/(25.00)$.

How It Works

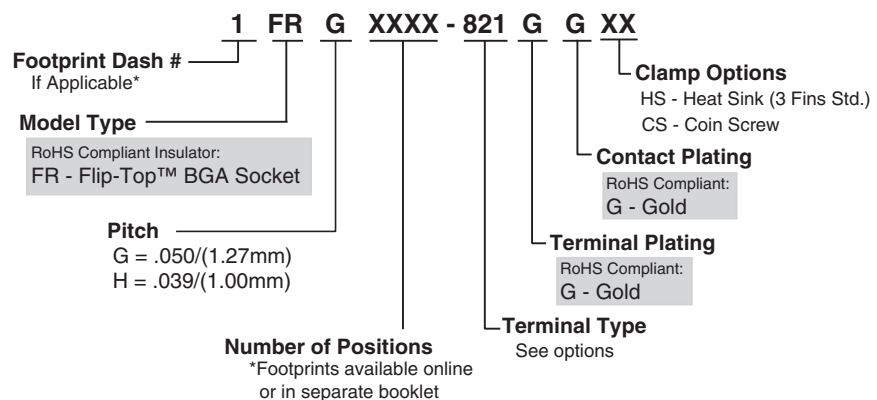


SMT models are shipped un-assembled to ease solderability. Thru-hole models are shipped fully assembled.

1. Lower assembly is soldered to PC board with no external hold-down mechanism. Thru-hole models may be soldered to PC board or plugged into a mating socket.
2. Upper assembly inserts easily to lower assembly by aligning guide posts and installing four (supplied) screws.
3. Finned heat sink or coin screw is screwed down to flush position.
4. Lid opens easily by pressing latch.
5. BGA device is inserted by aligning A1 position with chamfered corner of Flip-Top™ socket. Place support plate on top of device, close lid, engage heat sink or coin screw, and socket is ready for use.

Detailed Installation and General Usage Instructions are provided with product.

How To Order



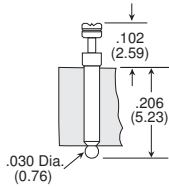
Standard Terminals

(for test, development and production applications)

SMT (Surface Mount)

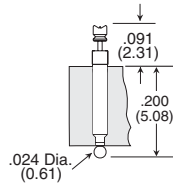
Tin/Lead: Type -690
Lead-free: Type -821

1.27mm pitch



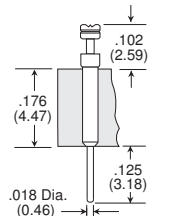
Tin/Lead: Type -752
Lead-free: Type -837

1.00mm pitch

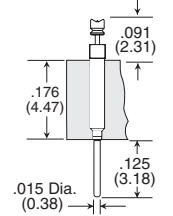


Thru-Hole

Type -708



Type -754



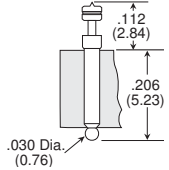
Standard Terminals

(for LGA or De-balled BGA device applications)

SMT (Surface Mount)

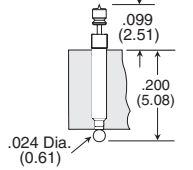
Tin/Lead: Type -713
Lead-free: Type -822

1.27mm pitch



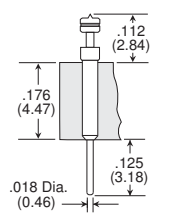
Tin/Lead: Type -762
Lead-free: Type -838

1.00mm pitch

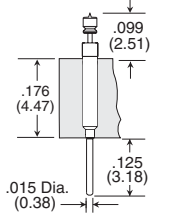


Thru-Hole

Type -712



Type -763



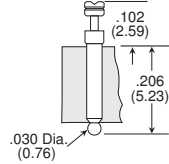
Standard Terminals

(for BGA Device Test Applications)

SMT (Surface Mount)

Tin/Lead: Type -659
Lead-free: Type -820

1.27mm pitch



Tin/Lead: Type -TBD
Lead-free: Type -TBD

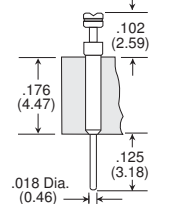
1.00mm pitch

Consult
Factory

Thru-Hole

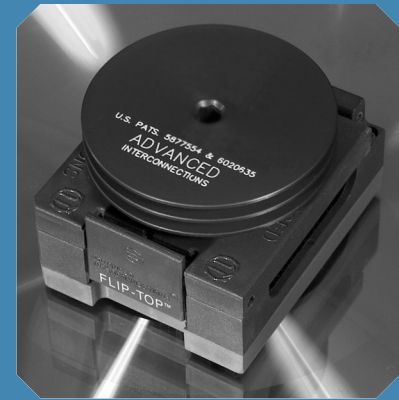
Type -657

Available with .016(0.41mm) Diam. tail; Type -709



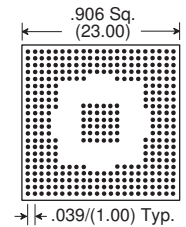
Type -TBD

Consult
Factory



Footprints:

360 Pins
Footprint Number 360-2



22 x 22 rows

- Full grid molded insulators populated to exact device pattern
- Over 900 footprints available - search online or request BGA Footprints Booklet
- Use our Build-A-Part feature or search in our online BGA Socket Finder™ at www.bgasockets.com

Available Online:

- RoHS Qualification Test Report
- Technical articles
- Test data
- CAD drawings
- BGA Footprints



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Cat. 16 Rev. 1